



Material Content Data Sheet



Sales Product Name	BTM7751G			Issued		27. July 2015		
MA#	MA001364474							
Package	PG-DSO-28-22			Weight*		810.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.033	1.36	1.36	13614	13614
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		89	
	non noble metal	zinc	7440-66-6	0.288	0.04		355	
	non noble metal	iron	7439-89-6	5.754	0.71		7100	
	non noble metal	copper	7440-50-8	233.637	28.83	29.59	288283	295827
wire	non noble metal	aluminium	7429-90-5	1.610	0.20	0.20	1986	1986
encapsulation	organic material	carbon black	1333-86-4	1.099	0.14		1356	
	plastics	epoxy resin	-	78.547	9.69		96918	
	inorganic material	silicondioxide	60676-86-0	469.634	57.94	67.77	579478	677752
leadfinish	non noble metal	tin	7440-31-5	4.975	0.61	0.61	6138	6138
plating	noble metal	silver	7440-22-4	0.678	0.08	0.08	836	836
glue	plastics	epoxy resin	-	0.546	0.07		673	
	noble metal	silver	7440-22-4	2.573	0.32	0.39	3174	3847
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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